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| **APPLICATION FORM****for KMM-VIN Research Fellowship 2013****Deadline for Submission: March 31, 2013****Personal Details:** |
| *Title:* |       |
| *Name:* |       |
| *Date of birth:* |       |
| *Nationality:* |       |
| *Institution:* |       |
| *Department:* |       |
| *Address:* |       |
| *Phone:* |       |
| *Fax:* |       |
| *Email:* |       |
| *Professional status* | *PhD student (date of inscription, supervisor’s name)*       *or**Researcher with PhD degree (date of PhD defense)*       |
| *Current research interest:* |      ***Please attach a short CV (1 page) and a List of Publications.*** |

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| **Host institution (KMM-VIN Member):** |
| *Name of host institution:* |       |
| *Duration of research stay:* |       |
| *Preferred beginning of research stay:*  |       2013 |
|  |
| ***Details of hosting person:*** |
| *Title:* |       |
| *Name:* |       |
| *Phone:* |       |
| *Email:* |       |
| ***Please attach a letter of acceptance of the host institution.*** |

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| **Description of the proposed research stay:** |
| *Title of the research stay:* |       |
| *Working plan summary (max. 200 words – for publication on KMM-VIN webpage)* |
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| *Objectives of research stay, detailed and specific working plan and proposed methods of investigation (max. 400 words)* |
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| *Any preliminary work already done by the applicant towards the proposed research fellowship (max. 150 words).* |
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| *Capacities (facilities, infrastructure, materials) needed to achieve the objectives of the planned research fellowship (max. 100 words).* |
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| *Expected outcome of the research fellowship with respect of objectives of KMM-VIN (potential of the research fellowship to develop lasting collaborations / joint projects with KMM-VIN host institution; future joint activities that are planned as a result of the research fellowship), (max. 150 words).* |
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| *Name of PhD Thesis supervisor / Head of Department* | *Date and signature* |
|       |       |